Notes on soldering

1. Type

SNT-4A, SNT-6A, SNT-6A(H), SNT-8A packages

2. Storage

The epoxy resin used in packages absorbs moisture in air, and the absorbed moisture vaporizes and expands during mounting. When the absorbed moisture amount becomes large, package cracks may occur.
For this reason, storage in lower humidity environment is recommended.
Packages adapted to the storage condition of the ambient temperature (Ta) of 5 to 30°C and relative humidity (RH) of 40 to 70%. This product is suitable for using it within one year.

3. Rinse

When rinse-free flux is applied, rinsing is not necessary. It may cause corrosion when residue of the active agents remained in the flux. Good selection of flux is indispensable to avoid corrosion.

4. Resistance to soldering heat (Reflow soldering, Soldering Iron)

4. 1 Reflow soldering

The temperature rise may be different in the resin and a terminal part due to the reflow soldering.
It is necessary to check the package surface temperature (resin) before setting the temperature profile.
Figure 1 shows the resistance to soldering heat condition for package (Reflow method).
Confirm the heat resistance of the package shown below. (Based on **JEDEC J-STD-020**)

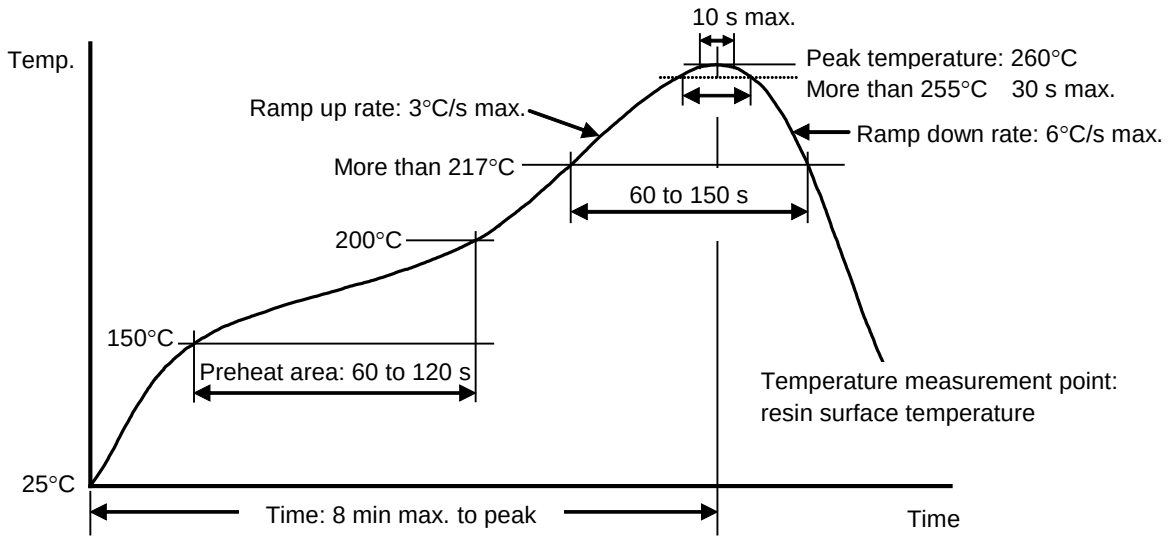

Figure 1 Resistance to soldering heat condition for package (Reflow method)

Number of maximum reflow cycles: Three times

4. 2 Soldering Iron

When using a soldering iron or heating collet, you should observe the following precautions only to a terminal part.
Each terminal part
① Maintain the maximum temperature of the soldering iron at 380°C for 5 seconds or less.
② Number of maximum Iron cycles: Two times

5. Caution on the wire pattern

Making the wire pattern under the package is possible. However, note that the package may be upraised due to the thickness made by the silk screen printing and of a solder resist on the pattern because this package does not have the standoff.